GigaDevice Semiconductor Inc.

GD32F190xx
ARM® Cortex®-M3 32-bit MCU

Datasheet

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1 General description

The GD32F190xx device belongs to the 5V value line of GD32 MCU family. It is a 32-bit general-purpose microcontroller based on the high performance ARM® Cortex®-M3 RISC core with best ratio in terms of processing power, reduced power consumption and peripheral set. The Cortex®-M3 is a next generation processor core which is tightly coupled with a Nested Vectored Interrupt Controller (NVIC), SysTick timer and advanced debug support.

The GD32F190xx device incorporates the ARM® Cortex®-M3 32-bit processor core operating at 72 MHz frequency with Flash accesses zero wait states to obtain maximum efficiency. It provides up to 64 KB on-chip Flash memory and up to 8 KB SRAM memory. An extensive range of enhanced I/Os and peripherals connected to two APB buses. The devices offer up to five general-purpose 16-bit timers, a general-purpose 32-bit timer, a basic timer, a PWM advanced-control timer, as well as standard and advanced communication interfaces: up to three SPIs, three I^2Cs and two USARTs, two I^2S, two CAN2.0B with a CAN PHY, and a segment LCD controller. Advanced analog peripherals including one 12-bit ADC, two 12-bit DACs, three OP-AMPs and two comparators.

The device operates from a 2.5 to 5.5V power supply and available in –40 to +85 °C temperature range. Several power saving modes provide the flexibility for maximum optimization between wakeup latency and power consumption, an especially important consideration in low power applications.

The above features make the GD32F190xx devices suitable for a wide range of applications, especially in areas such as industrial control, motor drives, user interface, power monitor and alarm systems, consumer and handheld equipment, home appliances, E-bike and so on.

2 Device overview

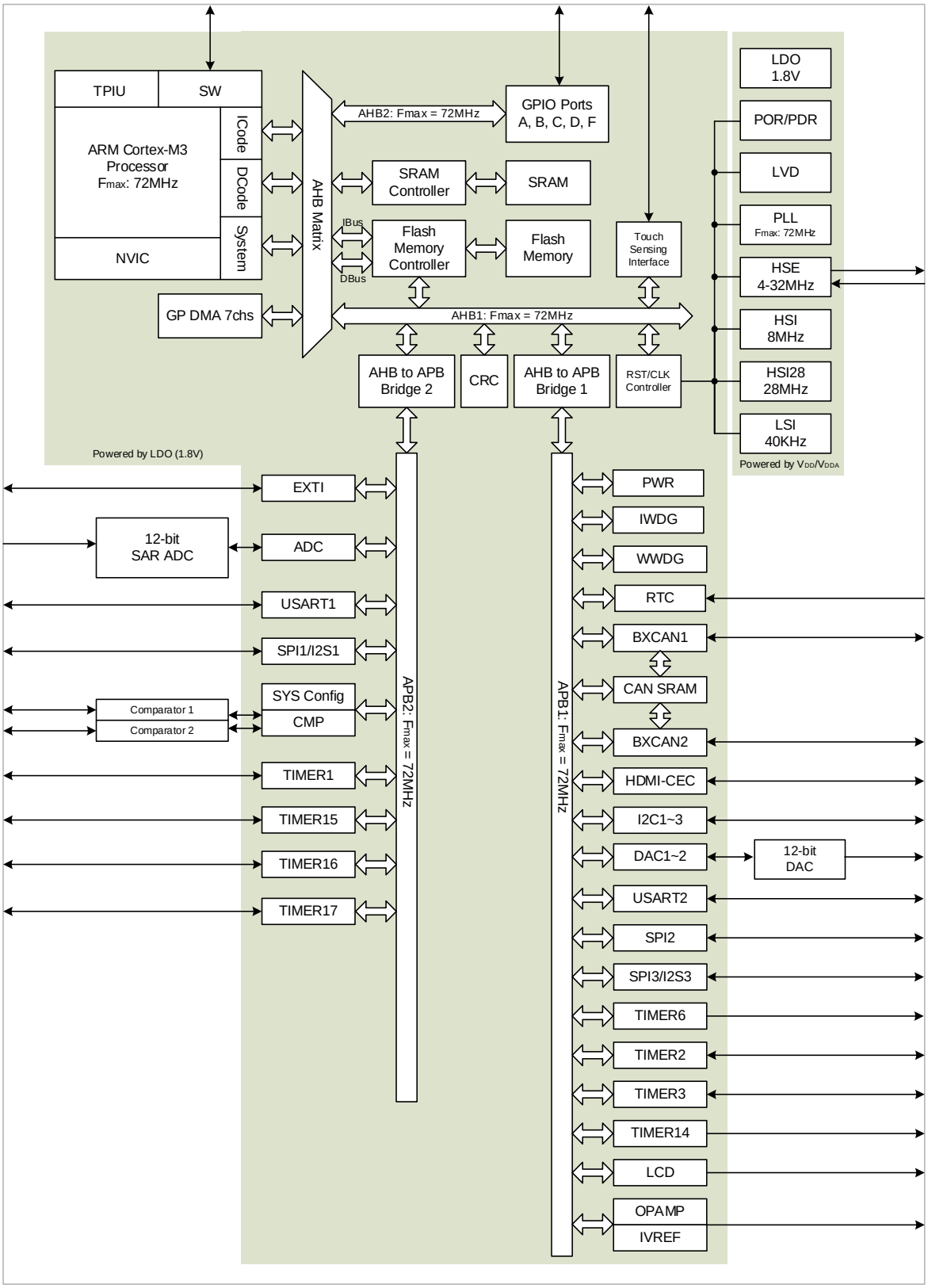
2.1 Device information

Table 1. GD32F190xx devices features and peripheral list

Part Number		GD32F190xx								
		T4	T6	T8	C4	C6	C8	R4	R6	R8
Flash (KB)		16	32	64	16	32	64	16	32	64
SRAM (KB)		4	6	8	4	6	8	4	6	8
Timers	32-bit GP	1	1	1	1	1	1	1	1	1
	16-bit GP	5	5	5	5	5	5	5	5	5
	16-bit Adv.	1	1	1	1	1	1	1	1	1
	16-bit Basic	1	1	1	1	1	1	1	1	1
	SysTick	1	1	1	1	1	1	1	1	1
	Watchdog	2	2	2	2	2	2	2	2	2
	RTC	1	1	1	1	1	1	1	1	1
Connectivity	USART	1	2	2	1	2	2	1	2	2
	I2C	1	1	3	1	1	3	1	1	3
	SPI	1	1	3	1	1	3	1	1	3
	I2S	1	1	2	1	1	2	1	1	2
	CAN 2.0B	2	2	2	2	2	2	2	2	2
	LCD	0	0	0	4x18	4x18	4x18	8x32	8x32	8x32
GPIO		28	28	28	39	39	39	55	55	55
Capacitive Touch Channels		14	14	14	17	17	17	18	18	18
OP-AMP		2	2	2	2	2	2	3	3	3
Analog Comparator		2	2	2	2	2	2	2	2	2
EXTI		16	16	16	16	16	16	16	16	16
ADC	Units	1	1	1	1	1	1	1	1	1
	Channels (Ext.)	10	10	10	10	10	10	16	16	16
	Channels (Int.)	3	3	3	3	3	3	3	3	3
DAC		2	2	2	2	2	2	2	2	2
Package		QFN36			LQFP48			LQFP64		

2.2 Block diagram

Figure 1. GD32F190xx block diagram



2.3 Pinouts and pin assignment

Figure 2. GD32F190Rx LQFP64 pinouts

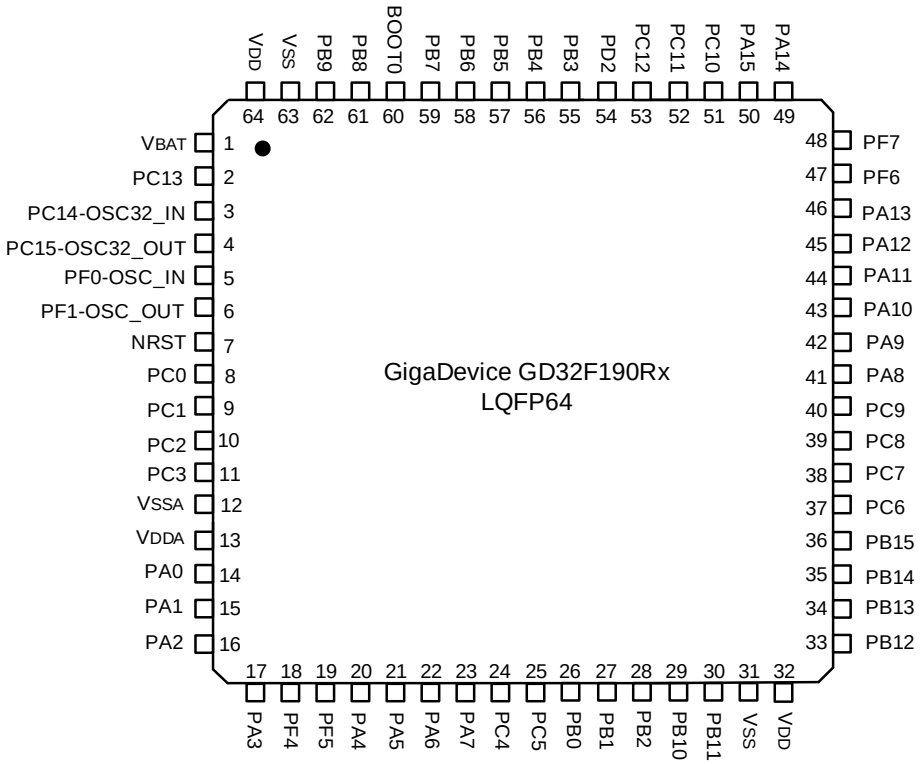


Figure 3. GD32F190Cx LQFP48 pinouts

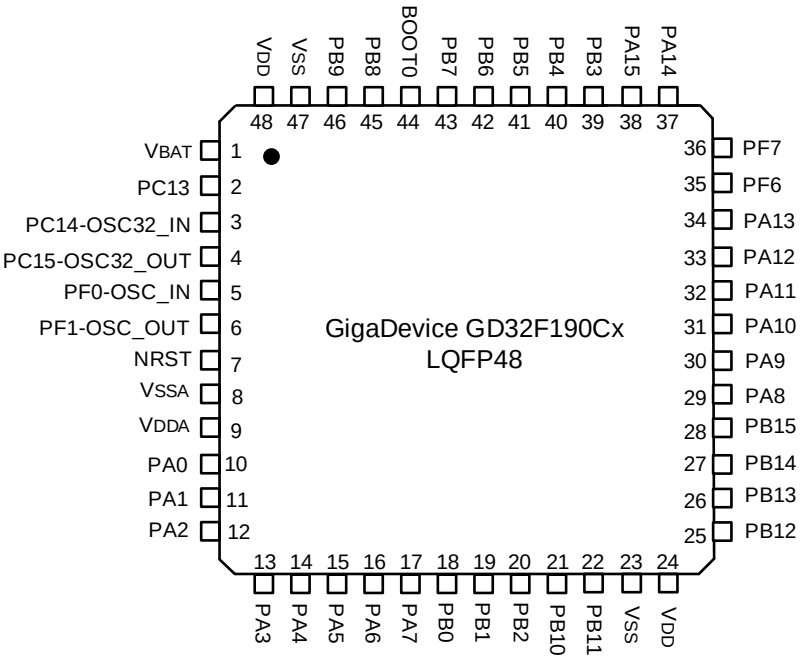
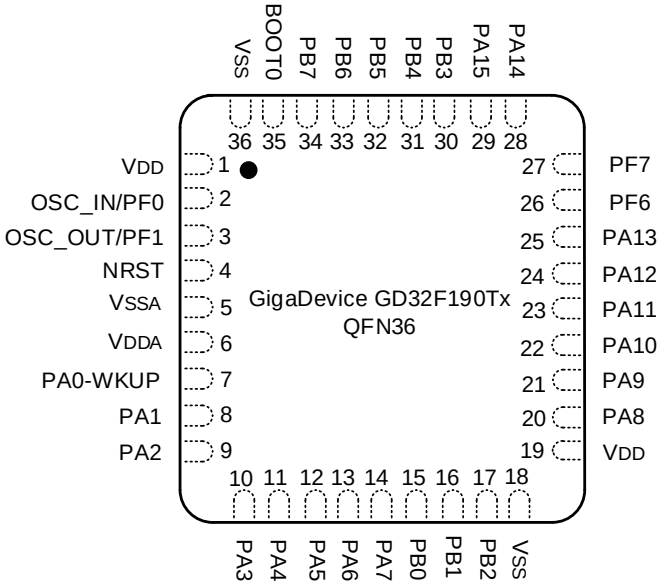
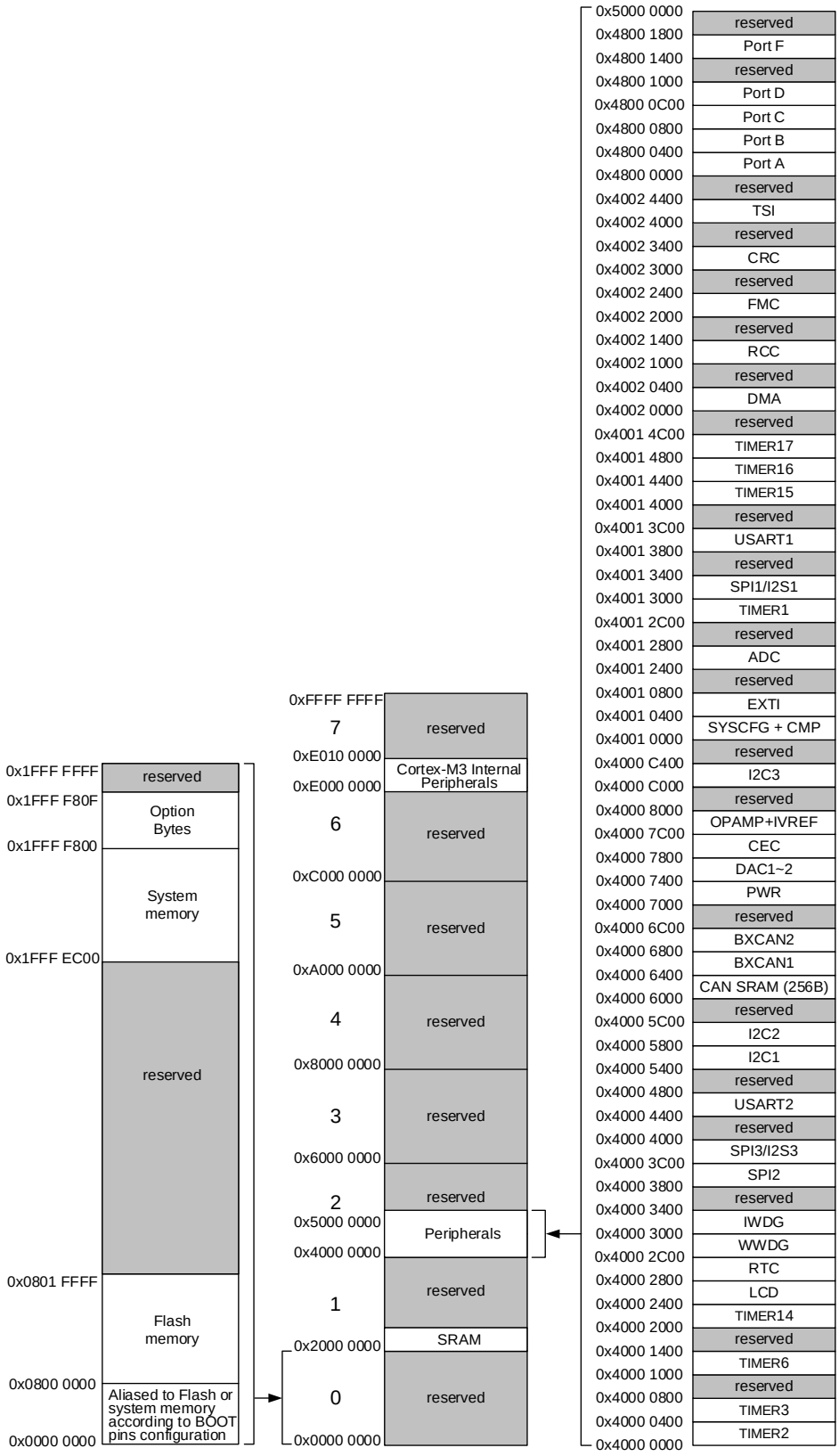


Figure 4. GD32F190Tx QFN36 pinouts



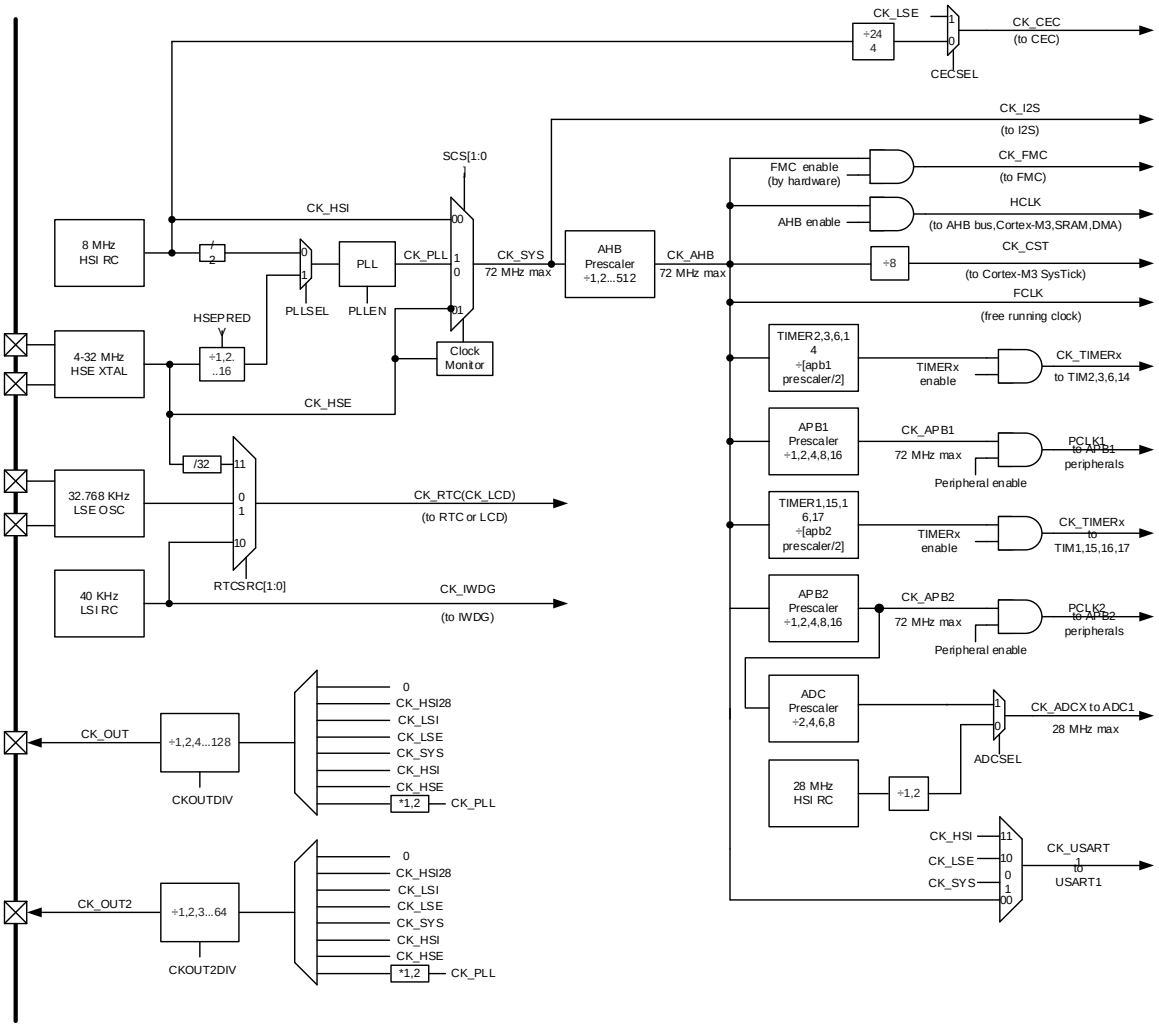
2.4 Memory map

Figure 5. GD32F190xx memory map



2.5 Clock tree

Figure 6. GD32F190xx clock tree



Legend:

HSE = High speed external clock

HSI = High speed internal clock

LSE = Low speed external clock

LSI = Low speed internal clock

2.6 Pin definitions

Table 2. GD32F190xx pin definitions

Pin Name	Pins			Pin Type(1)	I/O(2) Level	Functions description
	LQFP64	LQFP48	QFN36			
V_{LCD}/V_{BAT}	1	1	-	P		Default: V_{LCD}/V_{BAT}
PC13-TAMPER-RTC	2	2	-	I/O		Default: PC13 Additional: RTC_TAMP1, RTC_TS, RTC_OUT, WKUP2
PC14-OSC32_IN	3	3	-	I/O		Default: PC14 Additional: OSC32_IN
PC15-OSC32_OUT	4	4	-	I/O		Default: PC15 Additional: OSC32_OUT
PF0-OSC_IN	5	5	2	I/O	HVT	Default: PF0 Additional: OSC_IN
PF1-OSC_OUT	6	6	3	I/O	HVT	Default: PF1 Additional: OSC_OUT
NRST	7	7	4	I/O		Default: NRST
PC0	8	-	-	I/O		Default: PC0 Alternate: EVENTOUT, I2C3_SCL, SEG18 Additional: ADC_IN10
PC1	9	-	-	I/O		Default: PC1 Alternate: EVENTOUT, I2C3_SDA, SEG19 Additional: ADC_IN11, OPAMP3_VINP
PC2	10	-	-	I/O		Default: PC2 Alternate: EVENTOUT, I2C3_SMBA, SEG20 Additional: ADC_IN12, OPAMP3_VINM
PC3	11	-	-	I/O		Default: PC3 Alternate: EVENTOUT Additional: ADC_IN13, OPAMP3_VOUT, SEG21, I2C3_TXFRAME
V_{SSA}	12	8	5	P		Default: V_{SSA}
V_{DDA}	13	9	6	P		Default: V_{DDA}
PA0-WKUP	14	10	7	I/O		Default: PA0 Alternate: USART1_CTS(3), USART2_CTS(4), TM2_CH1_ETR, I2C2_SCL, CMP1_OUT, TSI_G1_IO1 Additional: ADC_IN0, RTC_TAMP2, WKUP1, CMP1_INM6
PA1	15	11	8	I/O		Default: PA1 Alternate: USART1_RTS(3), USART2_RTS(4), TM2_CH2, I2C2_SDA, EVENTOUT, SEG0, TSI_G1_IO2 Additional: ADC_IN1, CMP1_INP, OPAMP1_VINP
PA2	16	12	9	I/O		Default: PA2 Alternate: USART1_TX(3), USART2_TX(4), TM2_CH3, TM15_CH1, SEG1, CMP2_OUT, TSC_G1_IO3, I2C2_SMBA

Pin Name	Pins			Pin Type(1)	I/O(2) Level	Functions description
	LQFP64	LQFP48	QFN36			
						Additional: ADC_IN2, CMP2_INM6, OPAMP1_VINM
PA3	17	13	10	I/O		Default: PA3 Alternate: USART1_RX(3), USART2_RX(4), TM2_CH4, TM15_CH2, SEG2, TSI_G1_IO4, I2C2_TXFRAME Additional: ADC_IN3, CMP2_INP, OPAMP1_VOUT
PF4	18	-	-	I/O	HVT	Default: PF4 Alternate: EVENTOUT, SEG28
PF5	19	-	-	I/O	HVT	Default: PF5 Alternate: EVENTOUT, SEG29
PA4	20	14	11	I/O		Default: PA4 Alternate: SPI1_NSS, USART1_CK(3), USART2_CK(4), TM14_CH1, SPI2_NSS, I2S1_WS, TSI_G2_IO1, SPI3_NSS, I2S3_WS Additional: ADC_IN4, CMP1_INM4, CMP2_INM4, DAC1_OUT
PA5	21	15	12	I/O		Default: PA5 Alternate: SPI1_SCK, TM2_CH1_ETR, I2S1_CK, CEC, TSI_G2_IO2 Additional: ADC_IN5, CMP1_INM5, CMP2_INM5, DAC2_OUT, CANH
PA6	22	16	13	I/O		Default: PA6 Alternate: SPI1_MISO, TM3_CH1, TM1_BKIN, TM16_CH1, EVENTOUT, I2S1_MCK, CMP1_OUT, TSI_G2_IO3, SEG3 Additional: ADC_IN6, OPAMP2_VINP, CANL
PA7	23	17	14	I/O		Default: PA7 Alternate: SPI1_MOSI, TM3_CH2, TM14_CH1, TM1_CH1N, TM17_CH1, EVENTOUT, I2S1_SD, CMP2_OUT, TSI_G2_IO4, SEG4 Additional: ADC_IN7, OPAMP2_VINM
PC4	24	-	-	I/O		Default: PC4 Alternate: EVENTOUT, SEG22 Additional: ADC_IN14
PC5	25	-	-	I/O		Default: PC5 Alternate: TSI_G3_IO1, SEG23 Additional: ADC_IN15
PB0	26	18	15	I/O		Default: PB0 Alternate: TM3_CH3, TM1_CH2N, USART2_RX, EVENTOUT TSI_G3_IO2, SPI3_NSS, I2S3_WS, SEG5 Additional: ADC_IN8, VLCD_Rail3, IREF, OPAMP2_VOUT
PB1	27	19	16	I/O		Default: PB1 Alternate: TM3_CH4, TM14_CH1, TM1_CH3N, SPI2_SCK, TSI_G3_IO3, SEG6 Additional: ADC_IN9, VREF
PB2	28	20	17	I/O	HVT	Default: PB2 Alternate: TSI_G3_IO4 Additional: VLCD_Rail2

Pin Name	Pins			Pin Type(1)	I/O(2) Level	Functions description
	LQFP64	LQFP48	QFN36			
PB10	29	21	-	I/O	HVT	Default: PB10 Alternate: I2C2_SCL(4), CEC, TIM2_CH3, TSI_SYNC, I2C1_SCL(3), SEG10, SPI2_IO2
PB11	30	22	-	I/O	HVT	Default: PB11 Alternate: I2C2_SDA(4), TM2_CH4, EVENTOUT, TSI_G6_IO1, I2C1_SDA(3), SEG11, SPI2_IO3
V_{SS}	31	23	18	P		Default: V_{SS}
V_{DD}	32	24	19	P		Default: V_{DD}
PB12	33	25	-	I/O	HVT	Default: PB12 Alternate: SPI1_NSS(3), SPI2_NSS(4), TM1_BKIN, I2C2_SMBA, EVENTOUT, TSI_G6_IO2, SEG12, CAN2_RX Additional: VLCD_Rail1
PB13	34	26	-	I/O	HVT	Default: PB13 Alternate: SPI1_SCK(3), SPI2_SCK(4), TM1_CH1N, TSI_G6_IO3, SEG13, I2C2_TXFRAME, CAN2_TX
PB14	35	27	-	I/O	HVT	Default: PB14 Alternate: SPI1_MISO(3), SPI2_MISO(4), TM1_CH2N, TM15_CH1 TSI_G6_IO4, SEG14
PB15	36	28	-	I/O	HVT	Default: PB15 Alternate: SPI1_MOSI(3), SPI2_MOSI(4), TIM1_CH3N, TM15_CH1N, TM15_CH2, SEG15 Additional: RTC_REFIN
PC6	37	-	-	I/O	HVT	Default: PC6 Alternate: TM3_CH1, SEG24, I2C3_TXFRAME
PC7	38	-	-	I/O	HVT	Default: PC7 Alternate: TM3_CH2, I2C3_SCL, SEG25
PC8	39	-	-	I/O	HVT	Default: PC8 Alternate: TM3_CH3, I2C3_SDA, SEG26
PC9	40	-	-	I/O	HVT	Default: PC9 Alternate: TM3_CH4, I2C3_SMBA, SEG27, MCO2
PA8	41	29	20	I/O	HVT	Default: PA8 Alternate: USART1_CK, TM1_CH1, MCO, USART2_TX, EVENTOUT, COM0, I2C1_TXFRAME
PA9	42	30	21	I/O	HVT	Default: PA9 Alternate: USART1_TX, TM1_CH2, TM15_BKIN , I2C1_SCL, TSI_G4_IO1, COM1, SPI2_IO2
PA10	43	31	22	I/O	HVT	Default: PA10 Alternate: USART1_RX, TM1_CH3, TM17_BKIN, I2C1_SDA, TSI_G4_IO2, COM2, SPI2_IO3
PA11	44	32	23	I/O	HVT	Default: PA11 Alternate: USART1_CTS, TM1_CH4, EVENTOUT, CMP1_OUT, TSI_G4_IO3, CAN1_RX

Pin Name	Pins			Pin Type(1)	I/O(2) Level	Functions description
	LQFP64	LQFP48	QFN36			
PA12	45	33	24	I/O	HVT	Default: PA12 Alternate: USART1_RTS, TM1_ETR, EVENTOUT, CMP2_OUT, TSI_G4_IO4, CAN1_TX
PA13	46	34	25	I/O	HVT	Default: PA13/SWDAT Alternate: IR_OUT, SWDAT,SPI2_MISO, I2C1_SMBA
PF6	47	35	26	I/O	HVT	Default: PF6 Alternate: I2C2_SCL(4), I2C1_SCL(3), SEG30
PF7	48	36	27	I/O	HVT	Default: PF7 Alternate: I2C2_SDA(4), I2C1_SDA(3), SEG31
PA14	49	37	28	I/O	HVT	Default: PA14/SWCLK Alternate: USART1_TX(3), USART2_TX(4), SWCLK, SPI2_MOSI
PA15	50	38	29	I/O	HVT	Default: PA15 Alternate: SPI1_NSS , USART1_RX(3), USART2_RX(4), TM2_CH1_ETR, SPI2_NSS, EVENTOUT, I2S1_WS, SPI3_NSS, I2S3_WS, SEG17, I2C1_SMBA
PC10	51	-	-	I/O	HVT	Default: PC10 Alternate: SPI3_SCK, I2S3_CK, COM4, SEG28
PC11	52	-	-	I/O	HVT	Default: PC11 Alternate: SPI3_MISO, I2S3_MCK, COM5, SEG29
PC12	53	-	-	I/O	HVT	Default: PC12 Alternate: SPI3_MOSI, I2S3_SD, COM6, SEG30
PD2	54	-	-	I/O	HVT	Default: PD2 Alternate: TM3_ETR, COM7, SEG31
PB3	55	39	30	I/O	HVT	Default: PB3 Alternate: SPI1_SCK, TM2_CH2, EVENTOUT, I2S1_CK, TSI_G5_IO1, SPI3_SCK, I2S3_CK, SEG7, I2C1_TXFRAME
PB4	56	40	31	I/O	HVT	Default: PB4 Alternate: SPI1_MISO, TM3_CH1, EVENTOUT, I2S1_MCK, TSI_G5_IO2, SPI3_MISO, I2S3_MCK, SEG8, I2C3_SMBA
PB5	57	41	32	I/O	HVT	Default: PB5 Alternate: SPI1_MOSI, I2C1_SMBA, TM16_BKIN, TM3_CH2, I2S1_SD, SPI3_MOSI, I2S3_SD, SEG9, I2C3_TXFRAME, CAN2_RX
PB6	58	42	33	I/O	HVT	Default: PB6 Alternate: I2C1_SCL, USART1_TX, TM16_CH1N, TSI_G5_IO3, I2C3_SCL, CAN2_TX
PB7	59	43	34	I/O	HVT	Default: PB7 Alternate: I2C1_SDA, USART1_RX, TM17_CH1N, TSI_G5_IO4, I2C3_SDA
BOOT0	60	44	35	I		Default: BOOT0
PB8	61	45	-	I/O	HVT	Default: PB8 Alternate: I2C1_SCL, TM16_CH1, CEC, TSI_SYNC, SEG16, CAN1_RX

Pin Name	Pins			Pin Type(1)	I/O(2) Level	Functions description
	LQFP64	LQFP48	QFN36			
PB9	62	46	-	I/O	HVT	Default: PB9 Alternate: I2C1_SDA, IR_OUT, TM17_CH1, EVENTOUT, COM3, CAN1_TX
V_{SS}	63	47	36	P		Default: V_{SS}
V_{DD}	64	48	1	P		Default: V_{DD}

Notes:

1. Type: I = input, O = output, P = power.
2. I/O Level: HVT = High Voltage Tolerant.
3. This feature is available on GD32F190x4 devices only.
4. This feature is available on GD32F190x8 and GD32F190x6 devices only.

Table 3. Port A alternate functions summary

Pin Name	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF9	AF11
PA0		USART1_CTS(1) USART2_CTS(2)	TM2_CH1_ ETR	TSI_G1_IO1	I2C2_SCL			CMP1_O UT		
PA1	EVENTOUT	USART1_RTS(1) USART2_RTS(2)	TM2_CH2	TSI_G1_IO2	I2C2_SDA					SEG0
PA2	TM15_CH1	USART1_TX(1) USART2_TX(2)	TM2_CH3	TSI_G1_IO3	I2C2_SMBA			CMP2_O UT		SEG1
PA3	TM15_CH2	USART1_RX(1) USART2_RX(2)	TM2_CH4	TSI_G1_IO4	I2C2_TXFRA ME					SEG2
PA4	SPI1_NSS I2S1_WS	USART1_CK(1) USART2_CK(2)		TSI_G2_IO1	TM14_CH1	SPI3_NSS/ I2S3_WS	SPI2_NSS			
PA5	SPI1_SCK I2S1_CK	CEC	TM2_CH1_ ETR	TSI_G2_IO2						
PA6	SPI1_MISO I2S1_MCK	TM3_CH1	TM1_BKIN	TSI_G2_IO3		TM16_CH1	EVENTOUT	CMP1_O UT		SEG3
PA7	SPI1_MOSI I2S1_SD	TM3_CH2	TM1_CH1N	TSI_G2_IO4	TM14_CH1	TM17_CH1	EVENTOUT	CMP2_O UT		SEG4
PA8	MCO	USART1_CK	TM1_CH1	EVENTOUT	USART2_TX	I2C1_TXFR AME				COM0
PA9	TM15_BKIN	USART1_TX	TM1_CH2	TSI_G4_IO1	I2C1_SCL		SPI2_IO2			COM1
PA10	TM17_BKIN	USART1_RX	TM1_CH3	TSI_G4_IO2	I2C1_SDA		SPI2_IO3			COM2
PA11	EVENTOUT	USART1_CTS	TM1_CH4	TSI_G4_IO3				CMP1_O UT	CAN1_RX	
PA12	EVENTOUT	USART1_RTS	TM1_ETR	TSI_G4_IO4				CMP2_O UT	CAN1_TX	
PA13	SWDAT	IR_OUT				I2C1_SMBA	SPI2_MISO			
PA14	SWCLK	USART1_TX(1) USART2_TX(2)					SPI2_MOSI			
PA15	SPI1_NSS I2S1_WS	USART1_RX(1) USART2_RX(2)	TM2_CH1_ ETR	EVENTOUT	I2C1_SMBA	SPI3_NSS I2S3_WS	SPI2_NSS			SEG17

1. This feature is available on GD32F190x4 devices only.
2. This feature is available on GD32F190x8 and GD32F190x6 devices only.

Table 4. Port B alternate functions summary

Pin Name	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF9	AF11
PB0	EVENTOUT	TM3_CH3	TM1_CH2N	TSI_G3_IO2	USART2_RX	SPI3_NSS I2S3_WS				SEG5
PB1	TM14_CH1	TM3_CH4	TM1_CH3N	TSI_G3_IO3			SPI2_SCK			SEG6
PB2				TSI_G3_IO4						
PB3	SPI1_SCK I2S1_CK	EVETOUT	TM2_CH2	TSI_G5_IO1	I2C1_TXFRAME	SPI3_SCK I2S3_CK				SEG7
PB4	SPI1_MISO I2S1_MCK	TM3_CH1	EVENTOUT	TSI_G5_IO2	I2C3_SMBA	SPI3_MISO I2S3_MCK				SEG8
PB5	SPI1_MOSI I2S1_SD	TM3_CH2	TM16_BKIN	I2C1_SMBA	I2C3_TXFRAME	SPI3_MOSI I2S3_SD			CAN2_RX	SEG9
PB6	USART1_TX	I2C1_SCL	TM16_CH1N	TSI_G5_IO3	I2C3_SCL				CAN2_TX	
PB7	USART1_RX	I2C1_SDA	TM17_CH1N	TSI_G5_IO4	I2C3_SDA					
PB8	CEC	I2C1_SCL	TM16_CH1	TSI_SYNC					CAN1_RX	SEG16
PB9	IR_OUT	I2C1_SDA	TM17_CH1	EVENTOUT					CAN1_TX	COM3
PB10	CEC	I2C1_SCL(1) I2C2_SCL(2)	TM2_CH3	TSI_SYNC			SPI2_IO2			SEG10
PB11	EVENTOUT	I2C1_SDA(1) I2C2_SDA(2)	TM2_CH4	TSI_G6_IO1			SPI2_IO3			SEG11
PB12	SPI1_NSS(1) SPI2_NSS(2)	EVENTOUT	TM1_BKIN	TSI_G6_IO2	I2C2_SMBA				CAN2_RX	SEG12
PB13	SPI1_SCK(1) SPI2_SCK(2)		TM1_CH1N	TSI_G6_IO3	I2C2_TXFRAME				CAN2_TX	SEG13
PB14	SPI1_MISO(1) SPI2_MISO(2)	TM15_CH1	TM1_CH2N	TSI_G6_IO4						SEG14
PB15	SPI1_MOSI(1) SPI2_MOSI(2)	TM15_CH2	TM1_CH3N	TM15_CH1N						SEG15

1. This feature is available on GD32F190x4 devices only.
2. This feature is available on GD32F190x8 and GD32F190x6 devices only.

Table 5. Port C & D & F alternate functions summary

Pin Name	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF9	AF11
PC0	EVENTOUT	I2C3_SCL								SEG18
PC1	EVENTOUT	I2C3_SDA								SEG19
PC2	EVENTOUT	I2C3_SMBA								SEG20
PC3	EVENTOUT	I2C3_TXFRAME								SEG21
PC4	EVENTOUT									SEG22
PC5	TSI_G3_IO1									SEG23
PC6	TIM3_CH1	I2C3_TXFRAME								SEG24
PC7	TIM3_CH2	I2C3_SCL								SEG25
PC8	TIM3_CH3	I2C3_SDA								SEG26
PC9	TIM3_CH4	I2C3_SMBA		MCO2						SEG27
PC10	SPI3_SCK I2S3_CK									COM4 SEG28
PC11	SPI3_MISO I2S3_MCK									COM5 SEG29
PC12	SPI3_MOSI I2S3_SD									COM6 SEG30
PD2	TIM3_ETR									COM7 SEG31
PF4	EVENTOUT									SEG28
PF5	EVENTOUT									SEG29
PF6	I2C1_SCL(1) I2C2_SCL(2)									SEG30
PF7	I2C1_SDA(1) I2C2_SDA(2)									SEG31

1. This feature is available on GD32F190x4 devices only.
2. This feature is available on GD32F190x8 and GD32F190x6 devices only.

3 Functional description

3.1 ARM® Cortex®-M3 core

The Cortex®-M3 processor is the latest generation of ARM® processors for embedded systems. It has been developed to provide a low-cost platform that meets the needs of MCU implementation, with a reduced pin count and low-power consumption, while delivering outstanding computational performance and an advanced system response to interrupts.

- 32-bit ARM® Cortex®-M3 processor core
- Up to 72 MHz operation frequency
- Single-cycle multiplication and hardware divider
- Integrated Nested Vectored Interrupt Controller (NVIC)
- 24-bit SysTick timer

The Cortex®-M3 processor is based on the ARMv7 architecture and supports both Thumb and Thumb-2 instruction sets. Some system peripherals listed below are also provided by Cortex®-M3:

- Internal Bus Matrix connected with ICode bus, DCode bus, system bus, Private Peripheral Bus (PPB) and debug accesses (AHB-AP)
- Nested Vectored Interrupt Controller (NVIC)
- Flash Patch and Breakpoint (FPB)
- Data Watchpoint and Trace (DWT)
- Instrument Trace Macrocell (ITM)
- Serial Wire JTAG Debug Port (SWJ-DP)
- Trace Port Interface Unit (TPIU)

3.2 On-chip memory

- Up to 64 Kbytes of Flash memory
- Up to 8 Kbytes of SRAM with hardware parity checking

The ARM® Cortex®-M3 processor is structured in Harvard architecture which can use separate buses to fetch instructions and load/store data. 64 Kbytes of inner Flash and 8 Kbytes of inner SRAM at most is available for storing programs and data, both accessed (R/W) at CPU clock speed with zero wait states. The Figure 5. GD32F190xx memory map shows the memory map of the GD32F190xx series of devices, including code, SRAM, peripheral, and other pre-defined regions.

3.3 Clock, reset and supply management

- Internal 8 MHz factory-trimmed RC and external 4 to 32 MHz crystal oscillator
- Internal 40 KHz RC calibrated oscillator and external 32.768 KHz crystal oscillator
- Integrated system clock PLL
- 2.5 to 5.5 V application supply and I/Os
- Supply Supervisor: POR (Power On Reset), PDR (Power Down Reset), and low voltage detector (LVD)

The Clock Control Unit (CCU) provides a range of oscillator and clock functions. These include speed internal RC oscillator and external crystal oscillator, high speed and low speed two types. Several prescalers allow the frequency configuration of the AHB and two APB domains. The maximum frequency of the AHB and two APB domains is 72 MHz. See Figure 9 for details on the clock tree.

The Reset Control Unit (RCU) controls three kinds of reset: system reset resets the processor core and peripheral IP components. Power-on reset (POR) and power-down reset (PDR) are always active, and ensures proper operation starting from 1.95V and down to 1.9V. The device remains in reset mode when V_{DD} is below a specified threshold. The embedded low voltage detector (LVD) monitors the power supply, compares it to the voltage threshold and generates an interrupt as a warning message for leading the MCU into security.

Power supply schemes:

- V_{DD} range: 2.5 to 5.5 V, external power supply for I/Os and the internal regulator. Provided externally through V_{DD} pins.
- V_{DDA} range: 2.5 to 5.5 V, external analog power supplies for ADC, reset blocks, RCs and PLL. V_{DDA} and V_{SSA} must be connected to V_{DD} and V_{SS}, respectively.
- V_{BAT} range: 1.8 to 5.5 V, power supply for RTC, external clock 32 kHz oscillator and backup registers (through power switch) when V_{DD} is not present.

3.4 Boot modes

At startup, boot pins are used to select one of three boot options:

- Boot from main Flash memory (default)
- Boot from system memory
- Boot from on-chip SRAM

In default condition, boot from main Flash memory is selected. The boot loader is located in the internal boot ROM memory (system memory). It is used to reprogram the Flash memory by using USART1 in device mode.

3.5 Power saving modes

The MCU supports three kinds of power saving modes to achieve even lower power consumption. They are Sleep mode, Deep-sleep mode, and Standby mode. These operating modes reduce the power consumption and allow the application to achieve the best balance between the CPU operating time, speed and power consumption.

- **Sleep** mode
  In sleep mode, only the clock of CPU core is off. All peripherals continue to operate and any interrupt/event can wake up the system.
- **Deep-sleep** mode
  In Deep-sleep mode, all clocks in the 1.8V domain are off, and all of the high speed crystal oscillator (HSI, HSE) and PLL are disabled. Only the contents of SRAM and registers are retained. Any interrupt or wakeup event from EXTI lines can wake up the system from the Deep-sleep mode including the 16 external lines, the RTC alarm and the LVD output,. When exiting the Deep-sleep mode, the HSI is selected as the system clock.
- **Standby** mode
  In Standby mode, the whole 1.8V domain is power off, the LDO is shut down, and all of HSI, HSE and PLL are disabled. The contents of SRAM and registers (except Backup Registers) are lost. There are four wakeup sources for the Standby mode, including the external reset from NRST pin, the RTC alarm, the IWDG reset, and the rising edge on WKUP pin.

3.6 Analog to digital converter (ADC)

- 12-bit SAR ADC engine with up to 2M SPS conversion rate
- 12-bit, 10-bit, 8-bit or 6-bit configurable resolution
- Hardware oversampling ratio adjustable from 2 to 256x improves resolution to 16-bit
- Conversion range: V_{SSA} to V_{DDA} (3.0 to 5.5 V)
- Temperature sensor

A 12-bit 2M SPS multi-channel ADC are integrated in the device. It is a total of up to 16 multiplexed external channels with 2 internal channels for temperature sensor and voltage reference measurement. The conversion range is between 3.0 V < V_{DDA} < 5.5 V. An on-chip 16-bit hardware oversample scheme improves performances while off-loading the related computational burden from the MCU. An analog watchdog block can be used to detect the channels, which are required to remain within a specific threshold window. A configurable channel management block of analog inputs also can be used to perform conversions in single, continuous, scan or discontinuous mode to support more advanced usages.

The ADC can be triggered from the events generated by the general-purpose timers (TMx) and the advanced-control timer (TM1) with internal connection. The temperature sensor can be used to generate a voltage that varies linearly with temperature. It is internally connected

to the ADC_IN16 input channel which is used to convert the sensor output voltage into a digital value.

3.7 Digital to analog converter (DAC)

- Two 12-bit DAC converter of independent output channel
- 8-bit or 12-bit mode in conjunction with the DMA controller

The 12-bit buffered DAC channel is used to generate variable analog outputs. The DAC is designed with integrated resistor strings structure. The DAC channels can be triggered by the timer update outputs or EXTI with DMA support. The maximum output value of the DAC is V_{REF+}.

3.8 DMA

- 7 channel DMA controller
- Peripherals supported: Timers, ADC, SPIs, I^2Cs, USARTs, DAC, I^2Ss

The flexible general-purpose DMA controllers provide a hardware method of transferring data between peripherals and/or memory without intervention from the CPU, thereby freeing up bandwidth for other system functions. Three types of access method are supported: peripheral to memory, memory to peripheral, memory to memory

Each channel is connected to fixed hardware DMA requests. The priorities of DMA channel requests are determined by software configuration and hardware channel number. Transfer size of source and destination are independent and configurable.

3.9 General-purpose inputs/outputs (GPIOs)

- Up to 55 fast GPIOs, all mappable on 16 external interrupt vectors (EXTI)
- Analog input/output configurable
- Alternate function input/output configurable

There are up to 55 general purpose I/O pins (GPIO) in GD32F190xx, named PA0 ~ PA15 and PB0 ~ PB15, PC0 ~ PC15, PD2, PF0, PF1, PF4-PF7 to implement logic input/output functions. Each of the GPIO ports has related control and configuration registers to satisfy the requirements of specific applications. The external interrupts on the GPIO pins of the device have related control and configuration registers in the External Interrupt Control Unit (EXTI). The GPIO ports are pin-shared with other alternative functions (AFs) to obtain maximum flexibility on the package pins. Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions. All GPIOs are high-current capable except for analog inputs.

3.10 Timers and PWM generation

- One 16-bit advanced-control timer (TM1), one 32-bit general-purpose timer (TM2), five 16-bit general-purpose timers (TM3, TM14 ~ TM17), and one 16-bit basic timer (TM6)
- Up to 4 independent channels of PWM, output compare or input capture for each general-purpose timer (GPTM) and external trigger input
- 16-bit, motor control PWM advanced-control timer with programmable dead-time generation for output match
- Encoder interface controller with two inputs using quadrature decoder
- 24-bit SysTick timer down counter
- 2 watchdog timers (Independent watchdog and window watchdog)

The advanced-control timer (TM1) can be used as a three-phase PWM multiplexed on 6 channels. It has complementary PWM outputs with programmable dead-time generation. It can also be used as a complete general-purpose timer. The 4 independent channels can be used for input capture, output compare, PWM generation (edge- or center-aligned counting modes) and single pulse mode output. If configured as a general-purpose 16-bit timer, it has the same functions as the TMx timer. It can be synchronized with external signals or to interconnect with other GPTMs together which have the same architecture and features.

The general-purpose timer (GPTM) can be used for a variety of purposes including general time, input signal pulse width measurement or output waveform generation such as a single pulse generation or PWM output, up to 4 independent channels for input capture/output compare. TM2 is based on a 32-bit auto-reload up/downcounter and a 16-bit prescaler. TM3 is based on a 16-bit auto-reload up/downcounter and a 16-bit prescaler. TM14 ~ TM17 is based on a 16-bit auto-reload upcounter and a 16-bit prescaler. The GPTM also supports an encoder interface with two inputs using quadrature decoder.

The basic timer, known as TM6, is mainly used for DAC trigger generation. They can also be used as a simple 16-bit time base.

The GD32F190xx provides two watchdog peripherals, Independent watchdog and window watchdog. They offer a combination of high safety level, flexibility of use and timing accuracy.

The independent watchdog timer includes a 12-bit down-counting counter and a 8-bit prescaler, It is clocked from an independent 40 kHz internal RC and as it operates independently of the main clock, it can operate in stop and standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management.

The window watchdog is based on a 7-bit down counter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

The SysTick timer is dedicated for OS, but could also be used as a standard down counter. It

features:

- A 24-bit down counter
- Auto reload capability
- Maskable system interrupt generation when the counter reaches 0
- Programmable clock source

3.11 Real time clock (RTC)

- Independent binary-coded decimal (BCD) format timer/counter with five 32-bit backup registers.
- Calendar with sub-seconds, seconds, minutes, hours, week day, date, year and month automatically correction
- Alarm function with wake up from deep-sleep and standby mode capability
- On-the-fly correction for synchronization with master clock. Digital calibration with 1 ppm resolution for compensation of quartz crystal inaccuracy.

The real time clock is an independent timer which provides a set of continuously running counters in backup registers to provide a real calendar function, and provides an alarm interrupt or an expected interrupt. It is not reset by a system or power reset, or when the device wakes up from standby mode. A 20-bit prescaler is used for the time base clock and is by default configured to generate a time base of 1 second from a clock at 32.768 kHz from external crystal oscillator.

3.12 Inter-integrated circuit (I2C)

- Up to three I2C bus interfaces can support both master and slave mode with a frequency up to 400 kHz
- Provide arbitration function, optional PEC (packet error checking) generation and checking
- Supports 7-bit and 10-bit addressing mode and general call addressing mode
- Hardware support specifications of secure access and control module interface applied in validation for resident ID cards

The I2C interface is an internal circuit allowing communication with an external I2C interface which is an industry standard two line serial interface used for connection to external hardware. These two serial lines are known as a serial data line (SDA) and a serial clock line (SCL). The I2C module provides two data transfer rates: 100 kHz of standard mode or 400 kHz of the fast mode. The I2C module also has an arbitration detect function to prevent the situation where more than one master attempts to transmit data to the I2C bus at the same time. A CRC-8 calculator is also provided in I2C interface to perform packet error checking for I2C data.

3.13 Serial peripheral interface (SPI)

- Up to three SPI interfaces with a frequency of up to 30 MHz
- Support both master and slave mode
- Hardware CRC calculation and transmit automatic CRC error checking
- Quad wire configuration available in master mode (SPI2)

The SPI interface uses 4 pins, among which are the serial data input and output lines (MISO & MOSI), the clock line (SCK) and the slave select line (NSS). Both SPIs can be served by the DMA controller. The SPI interface may be used for a variety of purposes, including simplex synchronous transfers on two lines with a possible bidirectional data line or reliable communication using CRC checking.

3.14 Universal synchronous asynchronous receiver transmitter (USART)

- Up to two USARTs with operating frequency up to 9 MHz
- Supports both asynchronous and clocked synchronous serial communication modes
- IrDA SIR encoder and decoder support
- LIN break generation and detection
- ISO 7816-3 compliant smart card interface

The USART (USART1, USART2) are used to translate data between parallel and serial interfaces, provides a flexible full duplex data exchange using synchronous or asynchronous transfer. It is also commonly used for RS-232 standard communication. The USART includes a programmable baud rate generator which is capable of dividing the system clock to produce a dedicated clock for the USART transmitter and receiver. The USART also supports DMA function for high speed data communication.

3.15 Inter-IC sound (I2S)

- Up to two I2S bus Interfaces with sampling frequency from 8 kHz to 192 kHz, multiplexed with SPI1 and SPI3
- Support either master or slave mode

The Inter-IC sound (I2S) bus provides a standard communication interface for digital audio applications by 3-wire serial lines. GD32F190xx contain a I2S-bus interface that can be operated with 16/32 bit resolution in master or slave mode, pin multiplexed with SPI1 and SPI3. The audio sampling frequency from 8 kHz to 192 kHz is supported with less than 0.5% accuracy error.

3.16 HDMI CEC

- Hardware support Consumer Electronics Control (CEC) protocol (HDMI standard rev1.4)

The CEC protocol provides high-level control functions between the audiovisual products linked with HDMI cables. GD32F190xx contain a HDMI-CEC controller which has an independent clock domain and can wake up the MCU from deep-sleep mode on data reception.

3.17 Touch sensing interface (TSI)

- Supports up to 18 external electrodes by the sensing channels distributed over 6 analog I/O groups
- Programmable charging frequency and I/O pins
- Capability to wake up the MCU from power saving modes

Capacitive sensing technology can be used for the detection of a finger (or any conductive object) presence near an electrode. The capacitive variation of the electrode introduced by the finger can be measured by charging and detecting the voltage across the sampling capacitor. GD32F190xx contain a hardware touch sensing interface (TSI) and only requires few external components to operate. The sensing channels are distributed over 6 analog I/O groups including: Group1 (PA0 ~ PA3), Group2 (PA4 ~ PA7), Group3 (PC5, PB0 ~ PB2), Group4 (PA9 ~ PA12), Group5 (PB3, PB4, PB6, PA7) and Group6 (PB11 ~ PB14),

3.18 Comparators (CMP)

- Two fast rail-to-rail low-power comparators with software configurable
- Programmable reference voltage (internal, external I/O or DAC output pin)

Two Comparators (CMP) are implemented within the devices. Both comparators can wake up from deep-sleep mode to generate interrupts and breaks for the timers and also can be combined as a window comparator. The internal voltage reference is also connected to ADC_IN17 input channel of the ADC.

3.19 Operational amplifiers (OP-AMP)

- Rail-to-rail input and output voltage range
- Low input bias current, offset voltage and low power mode

GD32F190xx provides two operational amplifiers with external or internal follower routing capability (or even amplifier and filter capability with external components). When one operational amplifier is selected, one external ADC channel is used to enable output measurement.

3.20 LCD controller (LCD)

- Configurable frame frequency
- Blinking of individual segments or all segments
- Double buffer up to 8x32 bits registers for LCD_DATAx storage
- The contrast can also be adjusted by configuring dead time
- VLCD rails decoupling capability

The LCD controller directly drives LCD displays by creating the AC segment and common voltage signals automatically. It can drive the monochrome passive liquid crystal display (LCD) which composed of a plurality of segments (pixels or complete symbols) that can be converted to visible or invisible. The LCD controller can support up to 32 segments and 8 commons.

3.21 Controller area network (CAN)

- Two CAN2.0B interface with communication frequency up to 1 Mbit/s
- Internal main PLL for USB CLK compliantly
- A hardware CAN2.0B PHY integrated (CAN1)

Controller area network (CAN) is a method for enabling serial communication in field bus. The CAN protocol has been used extensively in industrial automation and automotive applications. It can receive and transmit standard frames with 11-bit identifiers as well as extended frames with 29-bit identifiers. Each CAN has three mailboxes for transmission and two FIFOs of three message deep for reception. It also provides 14 scalable/configurable identifier filter banks for selecting the incoming messages needed and discarding the others. The integrated hardware CAN PHY can be enabled by register setting and this mode only used for CAN1.

3.22 Debug mode

- Serial wire JTAG debug port (SWJ-DP)

The ARM® SWJ-DP Interface is embedded and is a combined JTAG and serial wire debug port that enables either a serial wire debug or a JTAG probe to be connected to the target.

3.23 Package and operation temperature

- LQFP64 (GD32F190Rx), LQFP48 (GD32F190Cx) and QFN36 (GD32F190Tx)
- Operation temperature range: -40°C to +85°C (industrial level)

4 Electrical characteristics

4.1 Absolute maximum ratings

The maximum ratings are the limits to which the device can be subjected without permanently damaging the device. Note that the device is not guaranteed to operate properly at the maximum ratings. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

Table 6. Absolute maximum ratings

Symbol	Parameter	Min	Max	Unit
V_{DD}	External voltage range	V_{SS} - 0.3	V_{SS} + 5.5	V
V_{DDA}	External analog supply voltage	V_{SSA} - 0.3	V_{SSA} + 5.5	V
V_{BAT}	External battery supply voltage	V_{SS} - 0.3	V_{SS} + 5.5	V
V_{IN}	Input voltage on 5V tolerant pin	V_{SS} - 0.3	V_{SS} + 7.5	V
	Input voltage on other I/O	V_{SS} - 0.3	5.5	V
I_{IO}	Maximum current for GPIO pins	—	25	mA
T_A	Operating temperature range	-40	+85	°C
T_{STG}	Storage temperature range	-55	+150	°C
T_J	Maximum junction temperature	—	125	°C

4.2 Recommended DC characteristics

Table 7. DC operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	Supply voltage	—	2.5	5.0	5.5	V
V_{DDA}	Analog supply voltage	Same as V_{DD}	2.5	5.0	5.5	V
V_{BAT}	Battery supply voltage	—	2.0	—	5.5	V

4.3 Power consumption

The power measurements specified in the tables represent that code with data executing from on-chip Flash with the following specifications.

Table 8. Power consumption characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{DD}	Supply current (Run mode)	V_{DD}=V_{DDA}=5.0V, HSE=8MHz, System clock=72 MHz, All peripherals enabled	—	59.23	—	mA
		V_{DD}=V_{DDA}=5.0V, HSE=8MHz, System clock =72 MHz, All peripherals disabled	—	38.71	—	mA
		V_{DD}=V_{DDA}=5.0V, HSE=8MHz, System clock =48 MHz, All peripherals enabled	-—	40.46	—	mA
		V_{DD}=V_{DDA}=5.0V, HSE=8MHz, System Clock =48 MHz, All peripherals disabled	—	26.72	—	mA
	Supply current (Sleep mode)	V_{DD}=V_{DDA}=5.0V, HSE=8MHz, CPU clock off, System clock=72MHz, All peripherals enabled	—	35.17	—	mA
		V_{DD}=V_{DDA}=5.0V, HSE=8MHz, CPU clock off, System clock=72MHz, All peripherals disabled	—	13.00	—	mA
	Supply current (Deep-Sleep mode)	V_{DD}=V_{DDA}=5.0V, Regulator in run mode, LSI on, RTC on, All GPIOs analog mode	—	119.81	—	µA
		V_{DD}=V_{DDA}=5.0V, Regulator in low power mode, LSI on, RTC on, All GPIOs analog mode	—	105.35	—	µA
	Supply current (Standby mode)	V_{DD}=V_{DDA}=5.0V, LSE off, LSI on, RTC on	—	11.08	—	µA
		V_{DD}=V_{DDA}=5.0V, LSE off, LSI on, RTC off	—	10.56	—	µA
		V_{DD}=V_{DDA}=5.0V, LSE off, LSI off, RTC off	—	8.54	—	µA
I_{BAT}	Battery supply current	V_{DD} not available, V_{BAT}=5.5 V, LSE on with external crystal, RTC on, Higher driving	—	2.30	—	µA
		V_{DD} not available, V_{BAT}=5.0 V, LSE on with external crystal, RTC on, Higher driving	—	2.06	—	µA
		V_{DD} not available, V_{BAT}=3.3 V, LSE on with external crystal, RTC on, Higher driving	—	1.56	—	µA
		V_{DD} not available, V_{BAT}=2.5 V, LSE on with external crystal, RTC on, Higher driving	—	1.41	—	µA
		V_{DD} not available, V_{BAT}=5.0 V, LSE on with external crystal, RTC on, Lower driving	—	1.32	—	µA
		V_{DD} not available, V_{BAT}=3.3 V, LSE on with external crystal, RTC on, Lower driving	—	0.88	—	µA
		V_{DD} not available, V_{BAT}=2.5 V, LSE on with external crystal, RTC on, Lower driving	—	0.75	—	µA

4.4 EMC characteristics

EMS (electromagnetic susceptibility) includes ESD (Electrostatic discharge, positive and negative) and FTB (Burst of Fast Transient voltage, positive and negative) testing result is given in the following table, based on the EMS levels and classes compliant with IEC 61000 series standard.

Table 9. EMS characteristics

Symbol	Parameter	Conditions	Level/Class
V_{ESD}	Voltage applied to all device pins to induce a functional disturbance	VDD = 5.0 V, TA = +25 °C conforms to IEC 61000-4-2	3B
V_{FTB}	Fast transient voltage burst applied to induce a functional disturbance through 100 pF on V_{DD} and V_{SS} pins	VDD = 5.0 V, TA = +25 °C conforms to IEC 61000-4-4	4A

EMI (Electromagnetic Interference) emission testing result is given in the following table, compliant with IEC 61967-2 standard which specifies the test board and the pin loading.

Table 10. EMI characteristics

Symbol	Parameter	Conditions	Tested frequency band	Conditions		Unit
				24M	48M	
S_{EMI}	Peak level	VDD = 5.0 V, TA = +25 °C, compliant with IEC 61967-2	0.1 to 2 MHz	<0	<0	dBµV
			2 to 30 MHz	-3.9	-2.8	
			30 to 130 MHz	-7.2	-8	
			130 MHz to 1GHz	-7	-7	

4.5 Power supply supervisor characteristics

Table 11. Power supply supervisor characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{POR}	Power on reset threshold	—	1.87	1.94	2.01	V
V_{PDR}	Power down reset threshold		1.82	1.89	1.96	V
V_{HYST}	PDR hysteresis		—	0.05	—	V
$T_{RSTTEMP}$	Reset temporization		—	2	—	ms

4.6 Electrical sensitivity

The device is strained in order to determine its performance in terms of electrical sensitivity. Electrostatic discharges (ESD) are applied directly to the pins of the sample. Static latch-up (LU) test is based on the two measurement methods.

Table 12. ESD characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model)	T_A=25 °C; JESD22-A114	—	—	7000	V
$V_{ESD(CDM)}$	Electrostatic discharge voltage (charge device model)	T_A=25 °C; JESD22-C101	—	—	1000	V

Table 13. Static latch-up characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
LU	I-test	T_A=25 °C; JESD78	—	—	±200	mA
	V_{supply} over voltage		—	—	8.25	V

4.7 External clock characteristics

Table 14. High speed external clock (HSE) generated from a crystal/ceramic characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{HSE}	High Speed External oscillator (HSE) frequency	V_{DD}=5.0V	4	8	32	MHz
C_{HSE}	Recommended load capacitance on OSC_IN and OSC_OUT	—	—	20	30	pF
R_{FHSE}	Recommended external feedback resistor between XTALIN and XTALOUT	—	—	200	—	KΩ
D_{HSE}	HSE oscillator duty cycle	—	30	50	70	%
I_{DDHSE}	HSE oscillator operating current	V_{DD}=5.0V, T_A=25°C	—	1.7	—	mA
t_{SUHSE}	HSE oscillator startup time	V_{DD}=5.0V, T_A=25°C	—	2	—	ms

Table 15. Low speed external clock (LSE) generated from a crystal/ceramic characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{LSE}	Low Speed External oscillator (LSE) frequency	V_{DD}=V_{BAT}=5.0V	—	32.768	1000	KHz
C_{LSE}	Recommended load capacitance on OSC32_IN and OSC32_OUT	—	—	—	15	pF
D_{LSE}	LSE oscillator duty cycle	—	30	50	70	%
I_{DDLSE}	LSE oscillator operating current	LSEDRV[1:0]=00	—	0.7	—	µA
		LSEDRV[1:0]=01	—	0.8	—	
		LSEDRV[1:0]=10	—	1.1	—	
		LSEDRV[1:0]=11	—	1.4	—	
t_{SULSE}	LSE oscillator startup time	V_{DD}=V_{BAT}=5.0V	—	3	—	s

4.8 Internal clock characteristics

Table 16. High speed internal clock (HSI) characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{HSI}	High Speed Internal Oscillator (HSI) frequency	V_{DD}=5.0V	—	8	—	MHz
ACC_{HSI}	HSI oscillator Frequency accuracy, Factory-trimmed	V_{DD}=5.0V, T_A=-40°C ~+105°C	-3.5	—	+3.0	%
		V_{DD}=5.0V, T_A=0°C ~ +85°C	-2.0	—	+2.0	%
		V_{DD}=5.0V, T_A=25°C	-1.0	—	+1.0	%
D_{HSI}	HSI oscillator duty cycle	V_{DD}=5.0V, f_{HSI}=8MHz	48	50	52	%
I_{DDHSI}	HSI oscillator operating current	V_{DD}=5.0V, f_{HSI}=8MHz	—	80	100	µA
t_{SUHSI}	HSI oscillator startup time	V_{DD}=5.0V, f_{HSI}=8MHz	1	—	2	us

Table 17. Low speed internal clock (LSI) characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{LSI}	Low Speed Internal oscillator (LSI) frequency	V_{DD}=V_{BAT}=5.0V, T_A=-40°C ~ +85°C	30	40	60	KHz
I_{DDLSI}	LSI oscillator operating current	V_{DD}=V_{BAT}=5.0V, T_A=25°C	—	1	2	µA
t_{SULSI}	LSI oscillator startup time	V_{DD}=V_{BAT}=5.0V, T_A=25°C	—	—	80	µs

4.9 PLL characteristics

Table 18. PLL characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{PLLIN}	PLL input clock frequency	—	1	8	25	MHz
f_{PLL}	PLL output clock frequency	—	16	—	72	MHz
t_{LOCK}	PLL lock time	—	—		200	μs
$Jitter_{PLL}$	Cycle to cycle Jitter	—			300	ps

4.10 Memory characteristics

Table 19. Flash memory characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
PE_{CYC}	Number of guaranteed program /erase cycles before failure (Endurance)	T_A=-40°C ~ +85°C	100	—	—	kcycles
t_{RET}	Data retention time	T_A=125°C	20	—	—	years
t_{PROG}	Word programming time	T_A=-40°C ~ +85°C	200	—	400	us
t_{ERASE}	Page erase time	T_A=-40°C ~ +85°C	60	100	450	ms
t_{MERASE}	Mass erase time	T_A=-40°C ~ +85°C	3.2	—	9.6	s

4.11 GPIO characteristics

Table 20. I/O port characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IL}	Standard IO Low level input voltage	V_{DD}=2.5V	—	—	0.83	V
		V_{DD}=3.3V	—	—	1.24	
		V_{DD}=5.0V	—	—	1.97	
		V_{DD}=5.5V	—	—	2.22	
	High Voltage tolerant IO Low level input voltage	V_{DD}=2.5V	—	—	0.65	V
		V_{DD}=3.3V	—	—	0.93	
		V_{DD}=5.0V	—	—	1.46	
		V_{DD}=5.5V	—	—	1.66	
V_{IH}	Standard IO High level input voltage	V_{DD}=2.5V	1.67	—	—	V
		V_{DD}=3.3V	2.01	—	—	
		V_{DD}=5.0V	2.91	—	—	
		V_{DD}=5.5V	3.13	—	—	
	High Voltage tolerant IO High level input voltage	V_{DD}=2.5V	1.42	—	—	V
		V_{DD}=3.3V	1.70	—	—	
		V_{DD}=5.0V	2.38	—	—	
		V_{DD}=5.5V	2.54	—	—	
V_{OL}	Low level output voltage	V_{DD}=2.5V, I_{IO}=8mA	—	—	0.29	V
		V_{DD}=3.3V, I_{IO}=8mA	—	—	0.22	
		V_{DD}=5.0V, I_{IO}=8mA	—	—	0.17	
		V_{DD}=5.5V, I_{IO}=8mA	—	—	0.16	
		V_{DD}=2.5V, I_{IO}=20mA	—	—	1.10	
		V_{DD}=3.3V, I_{IO}=20mA	—	—	0.59	
		V_{DD}=5.0V, I_{IO}=20mA	—	—	0.42	
		V_{DD}=5.5V, I_{IO}=20mA	—	—	0.40	
V_{OH}	High level output voltage	V_{DD}=2.5V, I_{IO}=8mA	2.24	—	—	V
		V_{DD}=3.3V, I_{IO}=8mA	3.12	—	—	
		V_{DD}=5.0V, I_{IO}=8mA	4.87	—	—	
		V_{DD}=5.5V, I_{IO}=8mA	5.37	—	—	
		V_{DD}=2.5V, I_{IO}=20mA	1.68	—	—	
		V_{DD}=3.3V, I_{IO}=20mA	2.80	—	—	
		V_{DD}=5.0V, I_{IO}=20mA	4.64	—	—	
		V_{DD}=5.5V, I_{IO}=20mA	5.17	—	—	
R_{PU}	Internal pull-up resistor	V_{IN}=V_{SS}	30	40	50	kΩ
R_{PD}	Internal pull-down resistor	V_{IN}=V_{DD}	30	40	50	kΩ

4.12 ADC characteristics

Table 21. ADC characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Operating voltage	—	3.0	5.0	5.5	V
V_{ADCIN}	ADC input voltage range	—	0	—	V_{REF+}	V
f_{ADC}	ADC clock	—	0.1	—	28	MHz
f_S	Sampling rate	12-bit	0.007	—	2	MSPS
		10-bit	0.008	—	2.3	
		8-bit	0.01	—	2.8	
		6-bit	0.013	—	3.5	
V_{IN}	Analog input voltage	16 external;3 internal	0	—	V_{DDA}	V
V_{REF+}	Positive Reference Voltage	—	—	V_{DDA}	—	V
V_{REF-}	Negative Reference Voltage	—	—	0	—	V
R_{AIN}	External input impedance	See ***Equation 1***	—	—	38	kΩ
R_{ADC}	Input sampling switch resistance	—	—	—	0.5	kΩ
C_{ADC}	Input sampling capacitance	No pin/pad capacitance included	—	5.2	—	pF
t_{CAL}	Calibration time	f_{ADC}=28MHz	—	3	—	μs
t_s	Sampling time	f_{ADC}=28MHz	0.053	—	9.554	μs
t_{CONV}	Total conversion time (including sampling time)	12-bit	—	14	—	1/ f_{ADC}
		10-bit	—	12	—	
		8-bit	—	10	—	
		6-bit	—	8	—	
t_{SU}	Startup time	—	—	—	1	μs

Equation 1: R_{AIN} max formula $$R_{AIN} < \frac{T_S}{f_{ADC} * C_{ADC} * \ln(2^{N+2})} - R_{ADC}$$

The formula above (Equation 1) is used to determine the maximum external impedance allowed for an error below 1/4 of LSB. Here N=12 (from 12-bit resolution).

Table 22. ADC $R_{AIN\ max}$ for f_{ADC}=28MHz

T_s (cycles)	t_s (us)	$R_{AIN\ max}$ (KΩ)
1.5	0.0536	0.5
7.5	0.2679	4.8
13.5	0.4821	9
28.5	1.018	19
41.5	1.482	28
55.5	1.982	38
71.5	2.554	N/A
239.5	8.554	N/A

Note: Guaranteed by design, not tested in production.

4.13 DAC characteristics

Table 23. DAC characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Operating voltage	—	2.5	5.0	5.5	V
R_{LOAD}	Resistive load	Resistive load with buffer ON	5	—	—	kΩ
R_O	Impedance output	Impedance output with buffer OFF	—	—	15	kΩ
C_{LOAD}	Capacitive load	Capacitive load with buffer ON	—	—	50	pF
DAC_OUT_{min}	Lower DAC_OUT voltage	Lower DAC_OUT voltage with buffer ON	0.2	—	—	V
		Lower DAC_OUT voltage with buffer OFF	0.5	—	—	mV
DAC_OUT_{max}	Higher DAC_OUT voltage	Higher DAC_OUT voltage with buffer ON	—	—	V_{DDA}-0.2	V
		Higher DAC_OUT voltage with buffer OFF	—	—	V_{DDA}-1LSB	V
I_{DDA}	DC current consumption in quiescent mode with no load	Middle code on the input	—	—	797	μA
		Worst code on the input	—	—	1237	
DNL	Differential non linearity	—	—	±2	—	LSB
INL	Integral non linearity	—	—	±4	—	LSB
Gain error	Gain error	—	—	±0.5	—	%
$T_{SETTLING}$	Settling time	C_{LOAD}≤50pF, R_{LOAD}≥5kΩ	—	0.6	0.8	μs
Update rate	Max frequency for a correct DAC_OUT change from code i to i±1LSB	C_{LOAD}≤50pF, R_{LOAD}≥5kΩ	—	—	4	MS/s
T_{WAKEUP}	Wakeup time from off state	C_{LOAD}≤50pF, R_{LOAD}≥5kΩ	—	0.8	1	μs
PSRR	Power supply rejection ratio	No R_{Load}, C_{LOAD}=50pF	—	-85	-75	dB

4.14 SPI characteristics

Table 24. SPI characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{SCK}	SCK clock frequency	—	—	—	30	MHz
$TSI_{K(H)}$	SCK clock high time	—	19	—	—	ns
$TSI_{K(L)}$	SCK clock low time	—	19	—	—	ns
SPI master mode						
$t_{V(MO)}$	Data output valid time	—	—	—	25	ns
$t_{H(MO)}$	Data output hold time	—	2	—	—	ns
$t_{SU(MI)}$	Data input setup time	—	5	—	—	ns
$t_{H(MI)}$	Data input hold time	—	5	—	—	ns
SPI slave mode						
$t_{SU(NSS)}$	NSS enable setup time	f_{PCLK}=54MHz	74	—	—	ns
$t_{H(NSS)}$	NSS enable hold time	f_{PCLK}=54MHz	37	—	—	ns
$t_{A(SO)}$	Data output access time	f_{PCLK}=54MHz	0	—	55	ns
$t_{DIS(SO)}$	Data output disable time	—	3	—	10	ns
$t_{V(SO)}$	Data output valid time	—	—	—	25	ns
$t_{H(SO)}$	Data output hold time	—	15	—	—	ns
$t_{SU(SI)}$	Data input setup time	—	5	—	—	ns
$t_{H(SI)}$	Data input hold time	—	4	—	—	ns

4.15 I2C characteristics

Table 25. I2C characteristics

Symbol	Parameter	Conditions	Standard mode		Fast mode		Unit
			Min	Max	Min	Max	
f_{SCL}	SCL clock frequency	—	0	100	0	400	KHz
$TSI_{L(H)}$	SCL clock high time	—	4.0	—	0.6	—	ns
$TSI_{L(L)}$	SCL clock low time	—	4.7	—	1.3	—	ns

4.16 USART characteristics

Table 26. USART characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{SCK}	SCK clock frequency	—	—	—	36	MHz
$TSI_{K(H)}$	SCK clock high time	—	13	—	—	ns
$TSI_{K(L)}$	SCK clock low time	—	13	—	—	ns

4.17 Operational amplifier characteristics

Table 27. OP-AMP characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Operating voltage	—	2.5	5.0	5.5	V
V_{CM}	Common mode voltage range	V_{DDA}=5.0	0.05	—	4.95	V
I_{DD}	Operating current	Normal mode	330	370	383	μA
		Low power mode	170	190	197	
I_{Load}	Drive current	Normal mode	0.2	22	33	mA
		Low power mode	0.6	24	34	
$V_{os\_cal\_range}$	V_{os} calibration range	—	—	—	±14	mV
V_{os_cal}	V_{os} after calibration	Normal/Low power mode	—	—	±1.2	mV
T_{wakeup}	Wakeup time	Normal mode	2.7	2.9	3.0	μS
		Low power mode	4.1	4.4	4.8	μS
SR	Slew rate	Normal,R_L=10kΩ, C_L=47pF	2	2.5	3.33	V/μS
		Low power mode	1.43	1.67	2	
CMRR	Common mode rejection ratio	Normal mode	—	93.9	—	dB
		Low power mode	—	90.4	—	
PSRR	Power supply rejection ratio	Normal mode	—	63.4	—	dB
		Low power mode	—	81.7	—	
GBW	Gain bandwidth	Normal, R_L=10kΩ, C_L=47pF	—	10.2	—	MHz
		Low power mode	—	5.0	—	
A0	Open-loop gain	Normal, 10kΩ<R_L<50kΩ	—	94.14	—	dB
		Low power mode	—	94	—	

4.18 Comparators characteristics

Table 28. CMP characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Operating voltage	—	2.5	5.0	5.5	V
V_{IN}	Input voltage range	—	0	—	V_{DDA}	V
V_{BG}	Scaler input voltage	—	—	1.2	—	V
V_{SC}	Scaler offset voltage	—	—	±5	±10	mV
t_D	Propagation delay for 200mv step with 100mV overdrive	Ultra low power mode	—	0.91	1.06	μS
		Low power mode	—	0.45	0.53	μS
		Medium power mode	—	0.16	0.20	μS
		High speed power mode	—	30	41	nS
	Propagation delay for full range step with 100mV overdrive	Ultra low power mode	—	1.47	1.64	μS
		Low power mode	—	0.77	0.87	μS
		Medium power mode	—	0.28	0.32	μS
		High speed power mode	—	42	54	nS
I_{DD}	Current consumption	Ultra low power mode	—	1.8	2.1	μA
		Low power mode	—	2.85	3.20	
		Medium power mode	—	7.40	7.99	
		High speed power mode	—	65.9	68.3	
V_{offset}	Offset error	—	—	±5	±10	mV
V_{hys}	No hysteresis	—	—	0	—	mV
	Low hysteresis	High speed power mode	7	8	11	
		All other power modes	5	8	14	
	Medium hysteresis	High speed power mode	13	16	21	
		All other power modes	11	16	30	
	High hysteresis	High speed power mode	26	32	43	
		All other power modes	20	32	60	

5 Package information

5.1 QFN package outline dimensions

Figure 7. QFN package outline

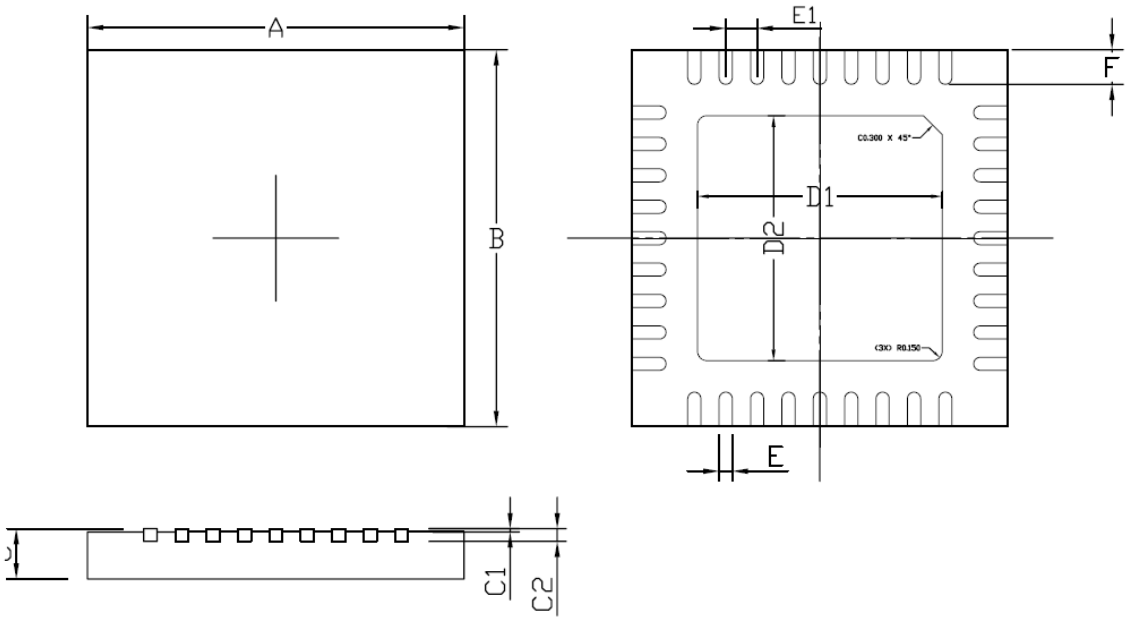


Table 29. QFN package dimensions

Symbol	QFN36		Symbol	QFN36	
	min	max		min	max
A	6.0 ± 0.1		D1	3.90 Typ	
B	6.0 ± 0.1		D2	3.90 Typ	
C	0.85	0.95	E	0.210 ± 0.025	
C1	0～0.050		E1	0.500 Typ	
C2	0.203 Typ		F	0.550 Typ	

(Original dimensions are in millmeters)

Note:

1. Formed lead shall be planar with respect to one another within 0.004 inches.
2. Both package length and width do not include mold flash and metal burr.

5.2 LQFP package outline dimensions

Figure 8. LQFP package outline

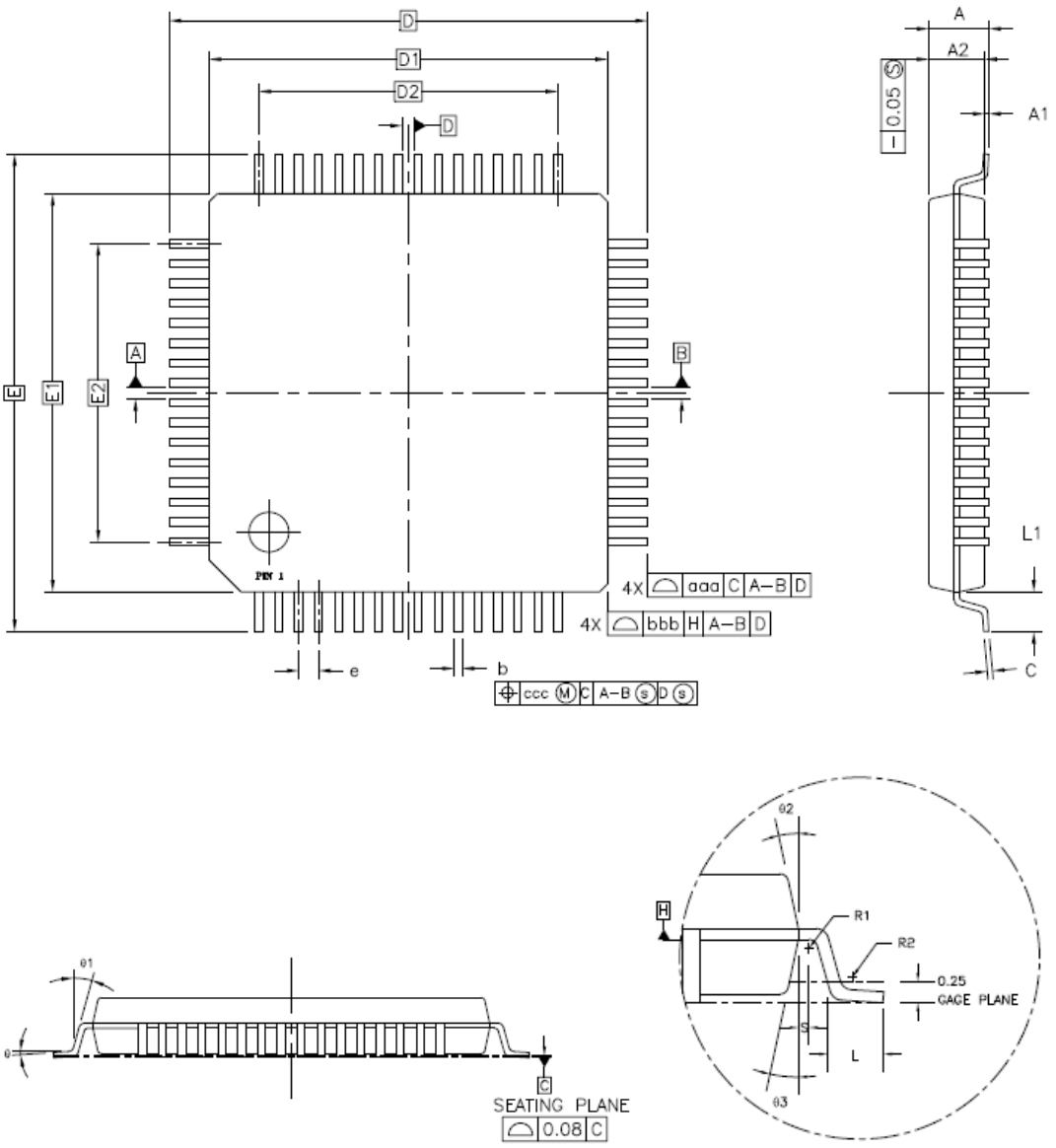


Table 30. LQFP package dimensions

Symbol	LQFP48		
	Min	Typ	Max
A	-	-	1.20
A1	0.05	-	0.15
A2	0.95	1.00	1.05
D	-	9.00	-
D1	-	7.00	-
E	-	9.00	-
E1	-	7.00	-
R1	0.08	-	-
R2	0.08	-	0.20
θ	0°	3.5°	7°
θ1	0°	-	-
θ2	11°	12°	13°
θ3	11°	12°	13°
c	0.09	-	0.20
L	0.45	0.60	0.75
L1	-	1.00	-
S	0.20	-	-
b	0.17	0.22	0.27
e	-	0.50	-
D2	-	5.50	-
E2	-	5.50	-
aaa	0.20		
bbb	0.20		
ccc	0.08		

Symbol	LQFP64		
	Min	Typ	Max
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	-	12.00	-
D1	-	10.00	-
E	-	12.00	-
E1	-	10.00	-
R1	0.08	-	-
R2	0.08	-	0.20
θ	0°	3.5°	7°
θ1	0°	-	-
θ2	11°	12°	13°
θ3	11°	12°	13°
c	0.09	-	0.20
L	0.45	0.60	0.75
L1	-	1.00	-
S	0.20	-	-
b	0.17	0.20	0.27
e	-	0.50	-
D2	-	7.50	-
E2	-	7.50	-
aaa	0.20		
bbb	0.20		
ccc	0.08		

(Original dimensions are in millmeters)

6 Ordering Information

Table 31. Part ordering code for GD32F190xx devices

Ordering code	Flash (KB)	Package	Package type	Temperature operating range
GD32F190T4U6	16	QFN36	Green	Industrial -40°C to +85°C
GD32F190T6U6	32	QFN36	Green	Industrial -40°C to +85°C
GD32F190T8U6	64	QFN36	Green	Industrial -40°C to +85°C
GD32F190C4T6	16	LQFP48	Green	Industrial -40°C to +85°C
GD32F190C6T6	32	LQFP48	Green	Industrial -40°C to +85°C
GD32F190C8T6	64	LQFP48	Green	Industrial -40°C to +85°C
GD32F190R4T6	16	LQFP64	Green	Industrial -40°C to +85°C
GD32F190R6T6	32	LQFP64	Green	Industrial -40°C to +85°C
GD32F190R8T6	64	LQFP64	Green	Industrial -40°C to +85°C

7 Revision History

Table 32. Revision history

Revision No.	Description	Date
1.0	Initial Release	Jan.8, 2016